

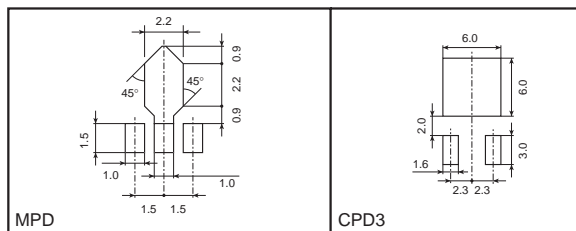
Soldering conditions

Surface mounted mold Diodes

● Reference to copper plate area dimension on printed circuit board

unit:mm

Terminal	2pin	Terminal	3pin	Terminal	4pin	Terminal	5pin	Terminal	6pin		
 UMD2	 PMD5	 EMD3	 UMD4	 UMD5	 UMD6	 EMD2	 PMDU	 UMD3	 SMD4	 SMD5	 SMD6
 VMD2	 TUMD2	 SMD3,SSD3	 EMD4	 EMD5	 EMD6	 PMDT	 VMN2	 VMD3	 TSMD5	 TSMD6	
 GMD2				 TUMD5							



*Copper plate area dimensions above are reference dimensions with being soldered with conditions below.

PCB FR-4,t=1.6mm
 Solder paste M705-GRN360-K2V
 Paste thickness 150mm
 Reflow soldering max. 250°C,10s

Solderability will depend on the soldering conditions,solder paste, paste thickness,soldering pad size, mount layout and so on. So, it is difficult for ROHM to refer to customer's soldering conditions.